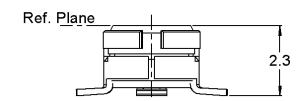
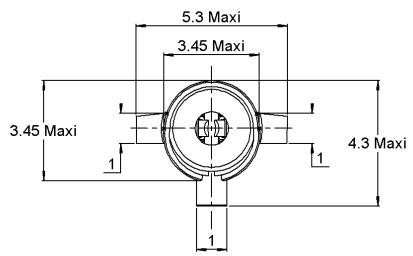
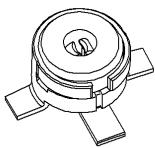




PAGE 1/5 ISSUE 03-02-17B SERIES MMS PART NUMBER R209408052







-@-Scale: 1/1

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Center contact	BERYLLIUM COPPER	GOLD 0.2 OVER TIN NICKEL 2
Outer contact		
Insulator	PTFE	
Gasket	-	
Others parts	-	
-	-	-
-	-	-



Technical Data Sheet

STRAIGHT JACK RECEPTACLE FOR PCB SMT TYPE REEL OF 500

PAGE 2 / 5	ISSUE 03-02-17B	SERIES MMS	PART NUMBER R209408052
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PACKAGING

Standard	Unit	Other	
500	Contact us	Contact us	

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} & \Omega \\ \text{Frequency} & & \textbf{0-6} & \text{GHz} \end{array}$

x F(GHz) Maxi √F(GHz) dB Maxi VSWR 0,0000 Insertion loss - F(GHz)) dB Maxi RF leakage NA Voltage rating 50 Veff Maxi Dielectric withstanding voltage 250 Veff mini Insulation resistance 500 $M\Omega$ mini

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating End
Axial force – Opposite end
Torque

NA N mini
NA N mini
N mini
N mini
N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 50 Cycles mini Weight 0,0590 g

ENVIRONMENTAL

Operating temperature -40/+125 °C
Hermetic seal NA Atm.cm3/s
Panel leakage NA

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

*1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06



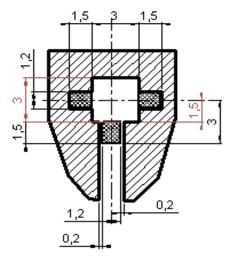


PAGE 3/5 ISSUE **03-02-17B** SERIES **MMS** PART NUMBER **R209408052**

MMS SERIES – INFORMATION

Coplanar line : Ground and signal are on the same side . Thicknass of PCB : 1mm The material of PCB is glass-epoxy composite. (Er = 4.8)

The sold er resist should be printed except for the land pattern on the PCB.



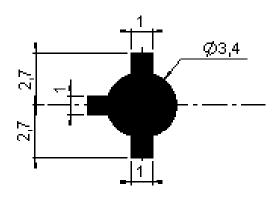


Pattern

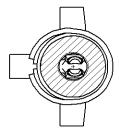


Land for solder paste

SHADOW OF MMS RECEPTACLE FOR VIDEO CAMERA



ASPIRATION AREA







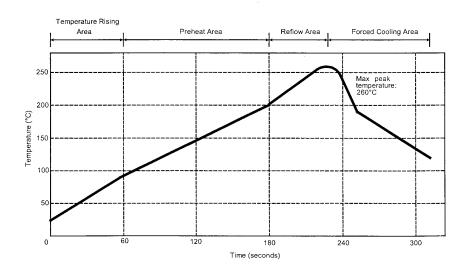


PAGE 4/5	ISSUE 03-02-17B	SERIES MMS	PART NUMBER R209408052
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SOLDER PROCEDURE

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec





PAGE **5/5** ISSUE **03-02-17B** SERIES MMS PART NUMBER **R209408052** A VIEW-Ø180-A REA FOR LABEL 4 ± 0.1 2 ± 0.1 8 ±0,10 Cover tape A VIEW (scale: 4)